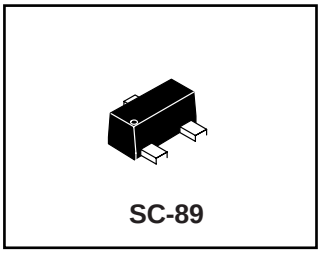
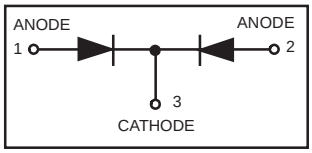
Dual Series Schottky Barrier Diodes

LRB715WT1G





●Applications

General purpose detection
High speed switching

●Features

1. Small surface mounting type.
2. Low V_F and low I_R
3. High reliability
4. We declare that the material of product compliance with RoHS requirements.

ORDERING INFORMATION

Device	Marking	Shipping
LRB715WT1G	3D	3000/Tape & Reel
LRB715WT3G	3D	10000/Tape & Reel

●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Peak reverse voltage	V_{RM}	40	V
DC reverse voltage	V_R	40	V
Mean rectifying current	I_O	30	mA
Peak forward surge current*	I_{FSM}	200	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–40~+125	°C

* 60 Hz for 1 ∿

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	–	–	0.37	V	I_F=1mA
Reverse current	I_R	–	–	1	μA	V_R=10V
Capacitance between terminals	C_T	–	2.0	–	pF	V_R=1V, f=1MHz

Note) ESD sensitive product handling required.

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Electrical characteristic curves (Ta=25°C)

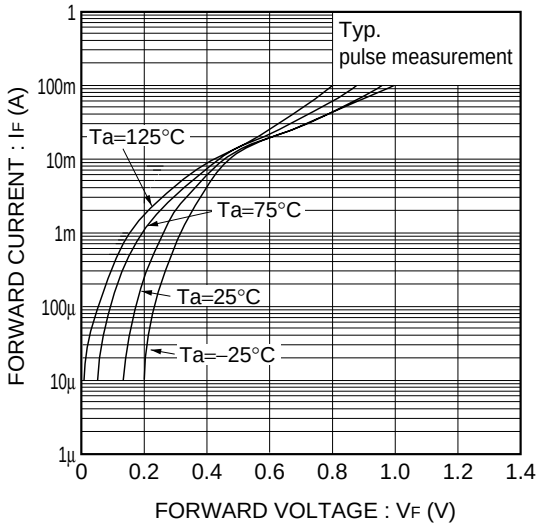

Fig. 1 Forward characteristics

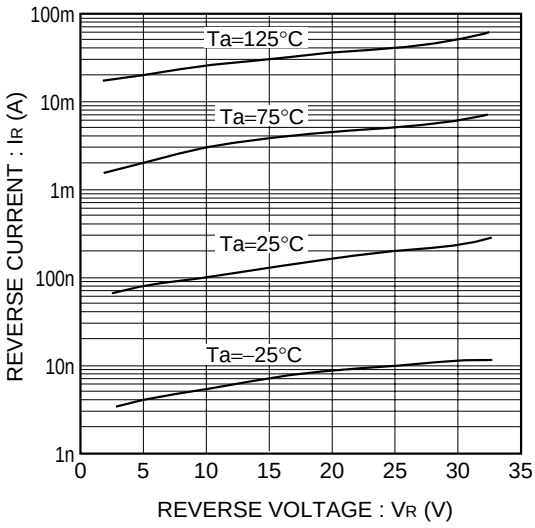

Fig. 2 Reverse characteristics

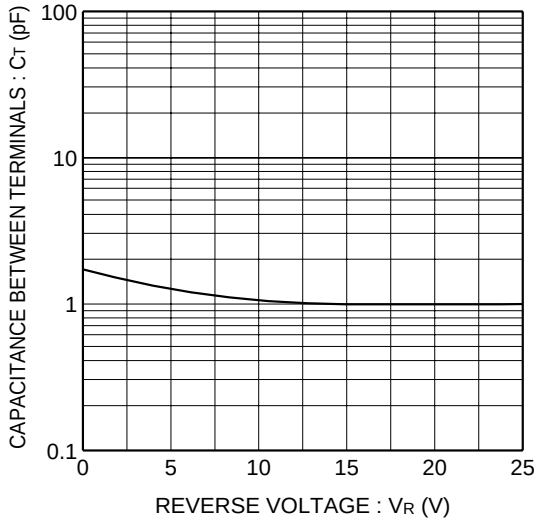

Fig. 3 Capacitance between terminals characteristics

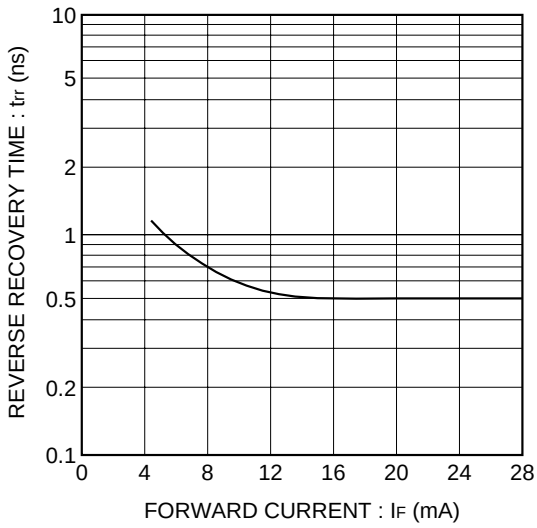

Fig. 4 Reverse recovery time characteristics

LRB715WT1G

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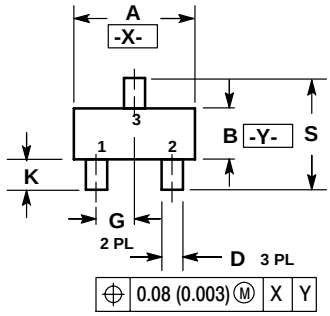
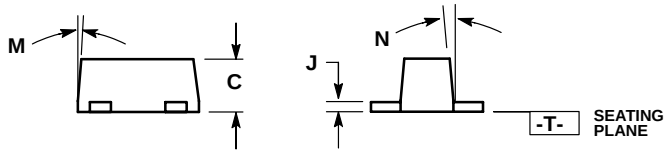
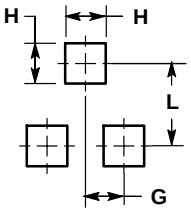




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50 BSC			0.020 BSC		
H	0.53 REF			0.021 REF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10 REF			0.043 REF		
M	---	---	10 °	---	---	10 °
N	---	---	10 °	---	---	10 °
S	1.50	1.60	1.70	0.059	0.063	0.067



RECOMMENDED PATTERN OF SOLDER PADS